

Date: 03/22/2017	DOC. No: SMBJ58CA-BD	Title: Bonding Diagram for SMBJ58CA IN SMB (DO-214AA)	
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Version	EFF.Date	Author	Description
A1	03/22/2017	Cao Lixin	Created

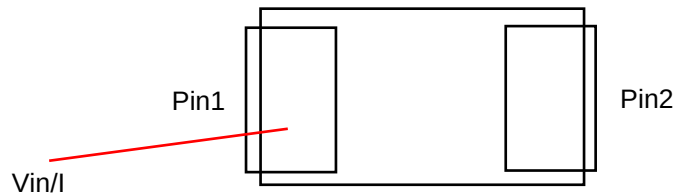
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1. Bonding Information

1. Chip name: SMBJ58CA
2. Die Size:1.8mmx1.8mm
3. Scribe:60um
4. Pad Size:1.58mmx1.58mm(Ag)
5. Die Thickness:200-210um
6. Package: SMB(DO-214AA)

2. Finish Test Specification

1. Test Circuit



2. Test Conditions

Table.1 SMBJ58CA Test Conditions

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_1	Breakdown Voltage	Pin1 to Pin2 $I_{(Pin1\ to\ Pin2)} = 1.0mA$ $T = 25\ ^\circ C$	64.4		71.2	V
V_2	Breakdown Voltage	Pin2 to Pin1 $I_{(Pin2\ to\ Pin1)} = 1.0mA$ $T = 25\ ^\circ C$	64.4		71.2	V
I_1	Leakage Current	Pin1 to Pin2 $V_{in}=58V$ $T = 25\ ^\circ C$			1	μA
I_2	Leakage Current	Pin2 to Pin1 $V_{in}=58V$ $T = 25\ ^\circ C$			1	μA